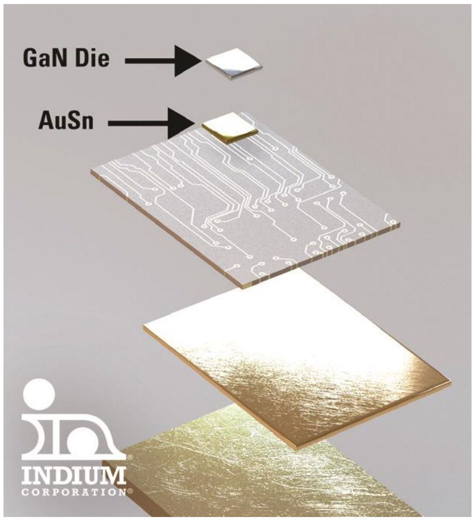
PRODUCT PREVIEW

Contact:
Jingya Huang, Corporate Communications
Indium Corporation
jhuang@indium.com
tel: +1.315.381.7566
Suite 301, 301 Woods Park Drive
Clinton, NY 13323 USA
www.indium.com

Date: May 29, 2025

Indium Corporation to Feature Precision Gold-Based Die-Attach Preforms at IMS 2025

Indium Corporation® will feature its high-reliability, gold-based precision die-attach preforms for critical laser and RF applications, as well as 5G communications, at the International Microwave Symposium, June 15-19, in San Francisco, CA.



Indium Corporation is a leading supplier of solder materials for laser and optical applications. Gold-based alloys are ideal for ensuring the highest possible performance and reliability for applications requiring a high-melting die-attach solder. In addition to meeting the demanding thermal and electrical requirements of high-reliability systems, they also provide the strongest resistance to corrosion and oxidation for long-lasting solder joints.

Among its featured products, Indium Corporation will showcase:

- AuLTRA® 75 is an off-eutectic AuSn preform solution (75Au/25Sn) designed to improve intermetallic reliability in applications using a die with a thicker gold plating, such as a GaN die used for high-frequency, high-power RF power amplifier devices for 5G and other critical military and aerospace wireless communications. AuLTRA® 75 helps improve the operation of these critical technologies by adjusting the final solder joint composition and improving wetting and voiding. The AuLTRA® product line is also available in 78Au/22Sn and 79Au/21Sn compositions.

- AuLTRA® Die-Attach Preforms offer the NEW Gold Standard—the highest level of quality available to deliver the best performance possible in critical, high-reliability die-attach applications. Features include:
    - Highly accurate thickness control

  - Precise edge quality
  - Optimized cleanliness
  - Default waffle pack method
  - Available for gold-based alloys

Additionally, Indium Corporation will feature the following gold-based die-attach solutions:

- AuLTRA® ThInFORMS® are 0.00035"-thick (0.00889mm or 8.89µm) 80Au/20Sn preforms that improve the overall operational efficiency of high-output lasers. AuLTRA® ThInFORMS® help combat common issues such as shorting and poor thermal transfer.

- AuLTRA® Fine Ribbon is the company's Indalloy®182 fine-grade precision ribbon for high-volume, fully automated laser diode assembly processes. For these auto-feed systems, the precision and high quality of the ribbon and spooling are of the utmost importance, along with long, continuous lengths. These features help minimize production downtime and facilitate an efficient, high-throughput process, resulting in a high-quality end product and low cost of ownership.

- AuLTRA® 3.2 is an air or nitrogen reflow, water-soluble AuSn solder paste optimized to handle the elevated processing temperatures of gold-based alloys. Perfect for high-power LED module array assemblies, it ensures consistent and repeatable printing performance, featuring a long stencil life and excellent tack. Along with consistently meeting printing and reflow demands, AuLTRA® 3.2 delivers superb wetting and low voiding.

- AuLTRA® 5.1 is a no-clean AuSn solder paste specifically formulated to endure the higher temperatures required by Au-based alloys. Ideal for high-power LED module array assemblies, this formulation provides a broad processing window and consistent print definition, even for ultra-fine pitches. Additionally, AuLTRA® 5.1 excels in wetting performance and void minimization while meeting rigorous printing and reflow standards.

To learn more about Indium Corporation's precision Au-based preforms, visit www.indium.com/products/gold-solder/gold-alloy-preforms/ or stop by booth #1532 at the show.

About International Microwave Symposium
For over 70 years, IMS has brought together a unique mix of international RF and microwave experts presenting the latest research and showcasing the newest products and services. IMS includes education and networking opportunities as well as an exhibition. Learn more at ims-ieee.org.

About Indium Corporation
Indium Corporation® is a premier materials refiner, smelter, manufacturer, and supplier to the global electronics, semiconductor, thin-film, and thermal management markets. Products include solders and fluxes; brazes; thermal interface materials; sputtering targets; indium, gallium, germanium, and tin metals and inorganic compounds; and NanoFoil®. Founded in 1934, the

company has global technical support and factories located in China, Germany, India, Malaysia, Singapore, South Korea, the United Kingdom, and the U.S.

For more information about Indium Corporation, visit www.indium.com or email jhuang@indium.com. You can also follow our experts, From One Engineer To Another® (#FOETA), at www.linkedin.com/company/indium-corporation/ or @IndiumCorp.

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